506583377 03/30/2021

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	RESUBMISSION
NATURE OF CONVEYANCE:	ASSIGNMENT
RESUBMIT DOCUMENT ID:	506566877

CONVEYING PARTY DATA

Name	Execution Date
TOMOKI SHIMIZU	02/10/2021

RECEIVING PARTY DATA

Name:	HITACHI, LTD.	
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City:	TOKYO	
State/Country:	te/Country: JAPAN	
Postal Code:	100-8280	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17208068

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ATTORNEY DOCKET NUMBER:	CKET NUMBER: WL-13119	
NAME OF SUBMITTER: JOHN R. MATTINGLY		
SIGNATURE: /John R. Mattingly/		
DATE SIGNED:	03/30/2021	

Total Attachments: 3

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PATENT 506583377 REEL: 055837 FRAME: 0669

ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me by Hitachi, Ltd.,

a corporation organized under the laws of Japan.

located at 6-5, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-8280 Japan

receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi, Ltd.,

its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

FILE STORAGE AND COMPUTER SYSTEM

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said Hitachi, Ltd.

its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hilachi, Ltd.,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)			Date Signed (署名目)	
1)	Tomoki Shlmizu	Tomoki SHIMIZU	February 10th, 2021	
2)				
3)				
4)				
5)				
6)			19 (19 1	
7)				
8)				

PATENT REEL: 055837 FRAME: 0670

RECORDED: 03/22/2021